

a semiconductor chip joined to the board in the state where its active surface is opposite to the board and its inactive surface which is a surface on the opposite side of the active surface is exposed;

an external connecting terminal electrically connected to the active surface of the semiconductor chip and projecting therefrom;

an underfill resin surrounding the external connecting terminal to form an outer peripheral underfill resin surface and covering at least a portion of the active surface; and

a protective resin covering a sidewall of the semiconductor chip and the outer peripheral underfill resin surface, the protective resin having a surface formed so as to be flush with the inactive surface of the semiconductor chip.

20. (NEW) A semiconductor device, comprising:

a semiconductor chip having a flat inactive surface and a flat opposite active surface with a sidewall extending peripherally about the semiconductor chip and between the active surface and the inactive surface;

a circuit board having a flat contacting surface disposed apart from and facially opposing the active surface of the semiconductor chip;

a plurality of bumps interposed between the semiconductor chip and the circuit board for electrically connecting the active surface of the semiconductor chip and the contacting surface of the circuit board and forming a clearance among the plurality of bumps and between the active surface of the semiconductor chip and the contacting surface of the circuit board;

an underfill resin disposed between the active surface of the semiconductor chip and the contacting surface of the circuit board for filling the clearance; and

a protective resin covering an outer peripheral surface of the underfill resin and the sidewall thereby surrounding the semiconductor chip and the outer peripheral surface of the underfill resin, the protective resin being in contact with and extending from the contacting surface of the circuit board to the inactive surface of the